

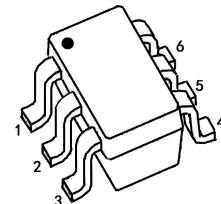
KY6801

-20V Dual P-Channel Mosfet

FEATURES

- $R_{DS(ON)} \leq 150\text{m}\Omega$ (120mΩ Typ.)
@ $V_{GS}=-4.5\text{V}$
- $R_{DS(ON)} \leq 230\text{m}\Omega$ (160mΩ Typ.)
@ $V_{GS}=-2.5\text{V}$

SOT-23-6L

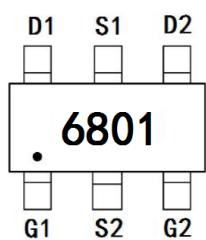


APPLICATIONS

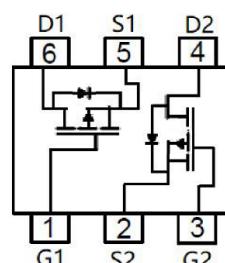
- Load Switch
- DC - DC Converter

1: G1 3: G2 5: S1
2: S2 4: D2 6: D1

MARKING



P-CHANNEL MOSFET



6801:Device Code

MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_a = 25^\circ\text{C}$	-20	-	V
V_{GS}	Gate-Source Voltage	$T_a = 25^\circ\text{C}$	-	± 12	V
I_D^*	Drain Current	$T_a = 25^\circ\text{C}, V_{GS} = -4.5\text{ V}$	-	-2.0	A
$I_{DM}^{*,**,**}$	Pulsed Drain Current	$T_a = 25^\circ\text{C}, V_{GS} = -2.5\text{ V}$	-	-8.0	A
P_{tot}^*	Total Power Dissipation	$T_a = 25^\circ\text{C}$	-	0.83	W
T_{stg}	Storage Temperature		-55	150	°C
T_J	Junction Temperature		-	150	°C
R_{eJA}^*	Thermal Resistance- Junction to Ambient		-	150	°C / W

Notes:

- * Surface Mounted on 1 in² pad area, t ≤ 10 sec
- ** Pulse width ≤ 10 μs, duty cycle ≤ 1 %
- *** limited by bonding wire

**Electrical Characteristics** ($T_a=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_{\text{DS}} = -250 \mu\text{A}$	-20	-	-	V
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{DS}} = -250 \mu\text{A}$	-0.4	-0.65	-1.0	V
I_{DSS}	Drain Leakage Current	$V_{\text{DS}} = -19 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	-	-	-1	μA
I_{GSS}	Gate Leakage Current	$V_{\text{GS}} = \pm 12 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	-	-	± 100	nA
$R_{\text{DS(ON)}}^{\text{a}}$	Channel On-State Resistance	$V_{\text{GS}} = -4.5 \text{ V}, I_{\text{D}} = -2.0 \text{ A}$	-	120	150	$\text{m}\Omega$
		$V_{\text{GS}} = -2.5 \text{ V}, I_{\text{D}} = -1.5 \text{ A}$	-	160	230	
Diode Characteristics						
V_{SD}^{a}	Diode Forward Voltage	$I_{\text{SD}} = -2.0 \text{ A}, V_{\text{GS}} = 0 \text{ V}$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{SD}} = -2.0 \text{ A}, dI_{\text{SD}} / dt = 100 \text{ A} / \mu\text{s}$	-	7.5	-	ns
Q_{rr}	Reverse Recovery Charge		-	2.5	-	nC
Dynamic Characteristics^b						
C_{iss}	Input Capacitance	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = -10 \text{ V}$ Frequency = 1 MHz	-	250	-	pF
C_{oss}	Output Capacitance		-	38	-	
C_{rss}	Reverse Transfer Capacitance		-	18	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}} = -10 \text{ V}, V_{\text{GEN}} = -4.5 \text{ V},$ $R_{\text{G}} = 3 \Omega, I_{\text{DS}} = -2.0 \text{ A}$	-	11	-	ns
t_{r}	Turn-on Rise Time		-	52	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	12	-	
t_{f}	Turn-off Fall Time		-	19	-	
Gate Charge Characteristics^b						
Q_{g}	Total Gate Charge	$V_{\text{GS}} = -4.5 \text{ V}, V_{\text{DS}} = -10 \text{ V},$ $I_{\text{DS}} = -2.0 \text{ A}$	-	5.3	-	nC
Q_{gs}	Gate-Source Charge		-	1.0	-	
Q_{gd}	Gate-Drain Charge		-	1.3	-	

Notes:

a : Pulse test ; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$

b : Guaranteed by design, not subject to production testing

Typical Characteristics

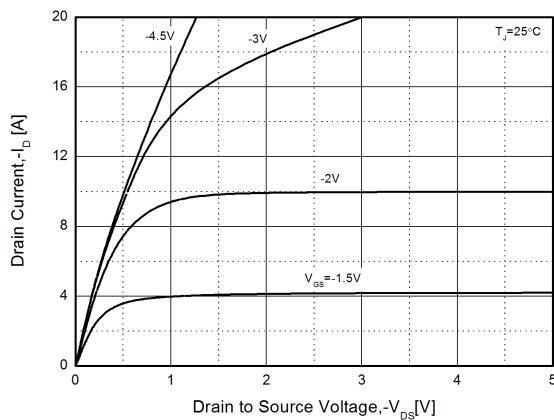


Figure1. Output Characteristics

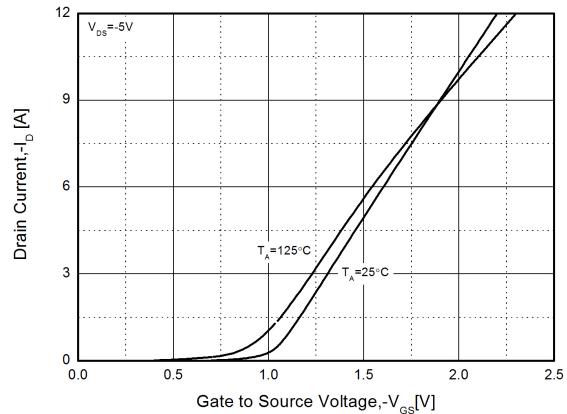


Figure2. Transfer Characteristics

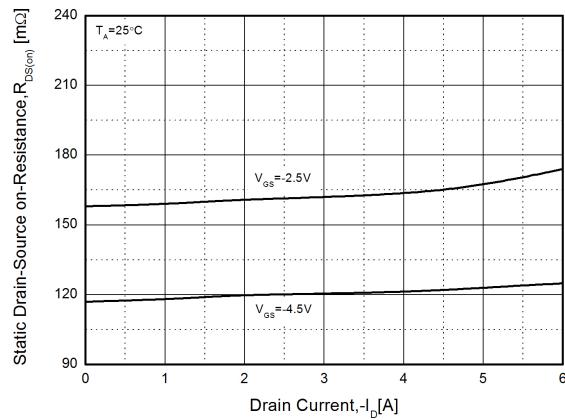


Figure3. Rdson-Drain Current

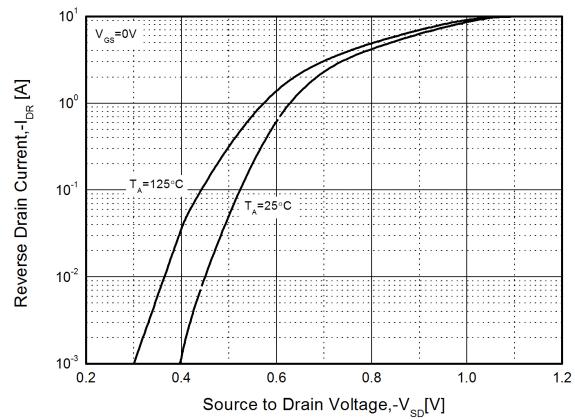


Figure4. Typical Source-Drain Diode Forward Voltage

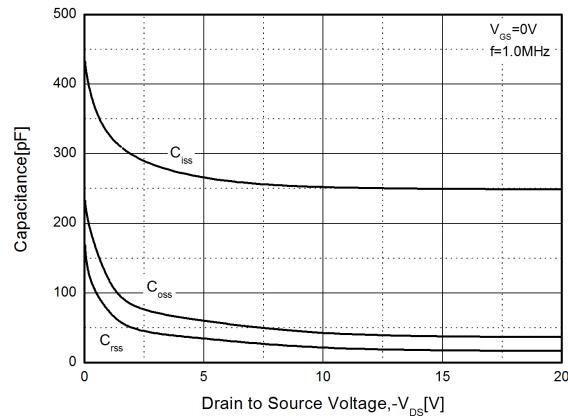


Figure5. Capacitance Characteristics

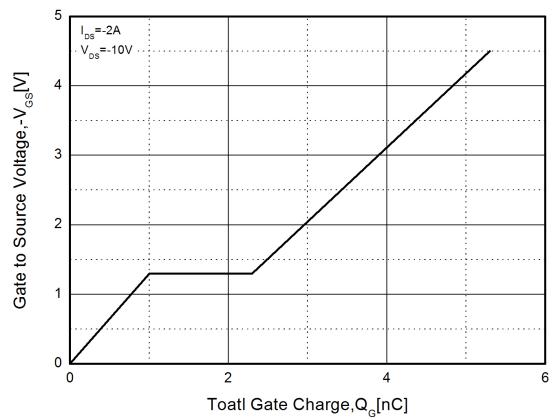


Figure6. Gate Charge

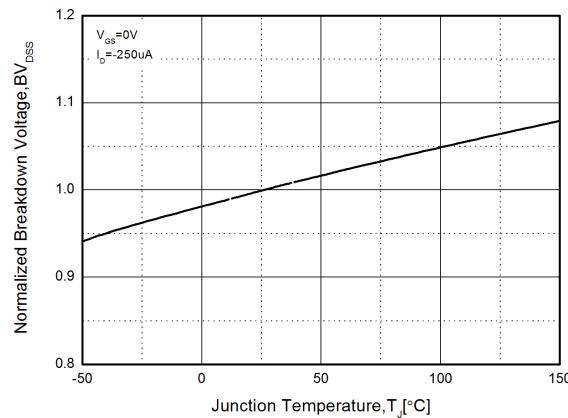


Figure7. Normalized Breakdown Voltage vs. Temperature

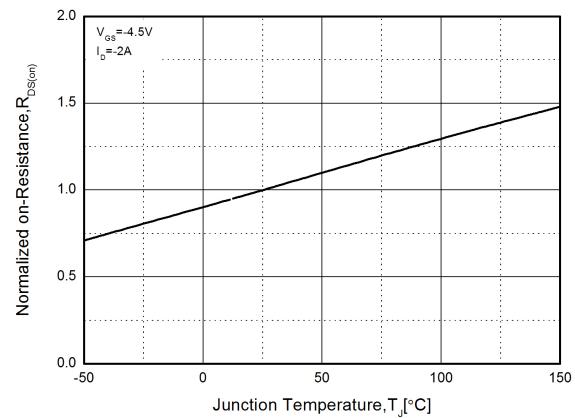


Figure8. Normalized on Resistance vs. Temperature

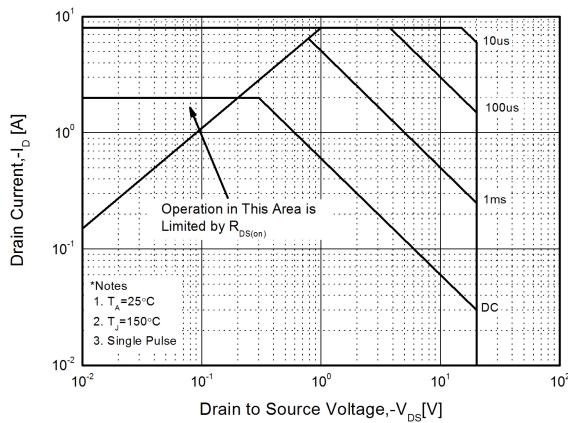


Figure9. Safe Operation Area

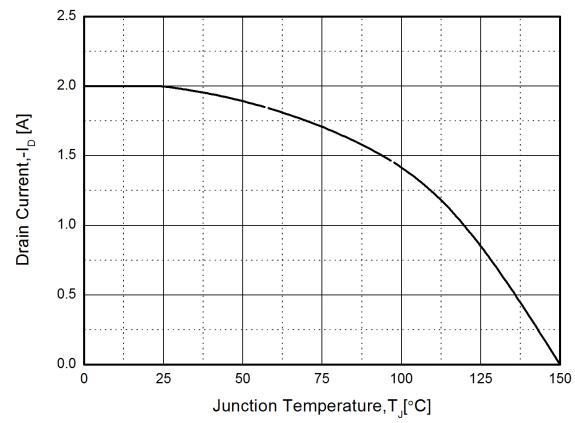


Figure10. Maximum Drain Current vs. Junction Temperature

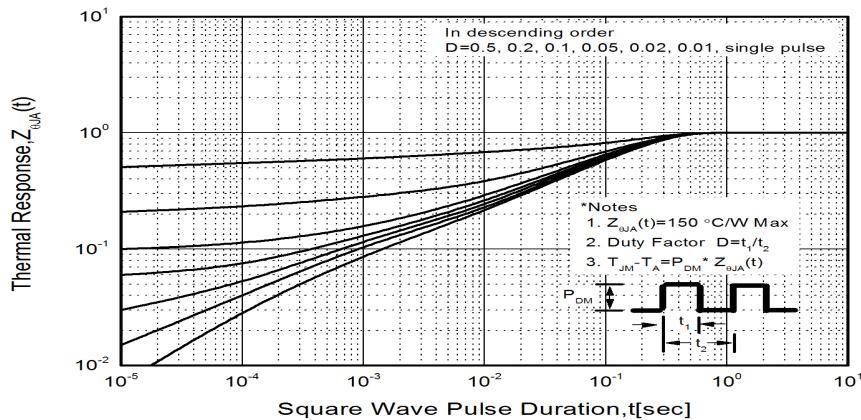


Figure11. Transient Thermal Response Curve

Typical Performance Characteristics

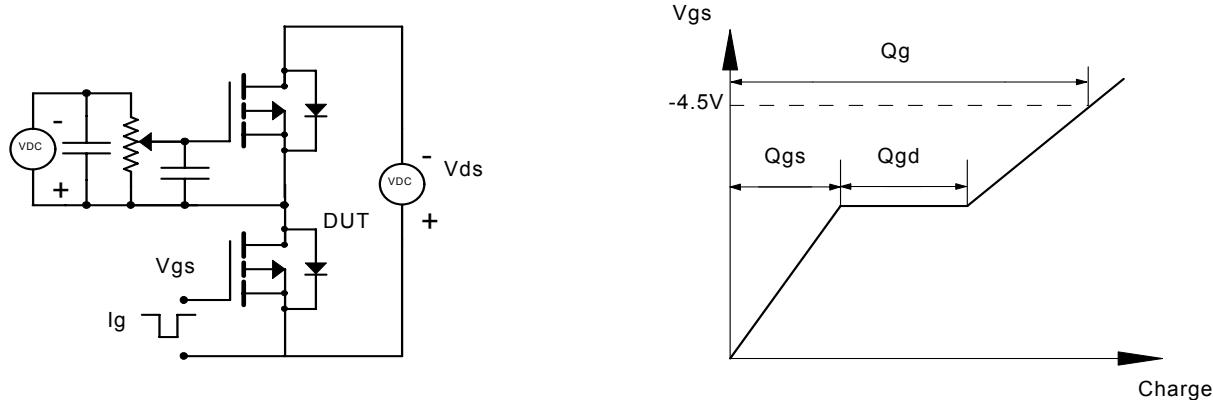


Figure1:Gate Charge Test Circuit & Waveform

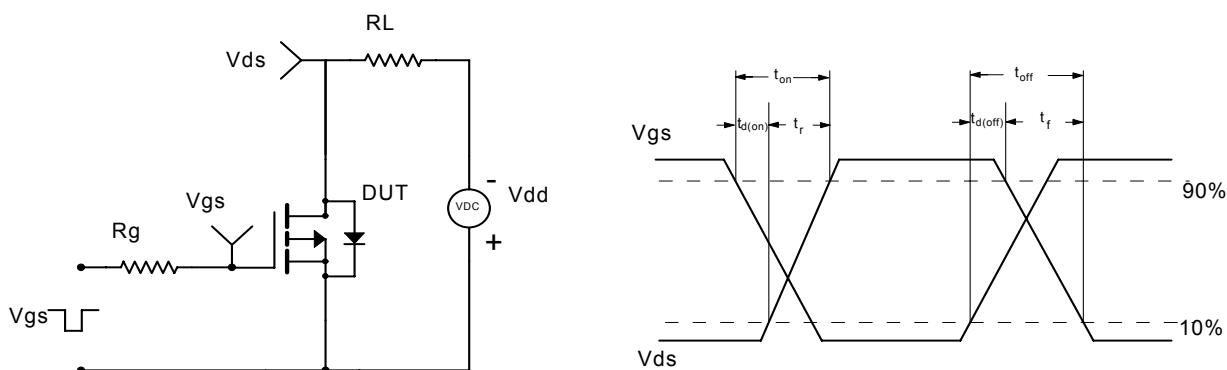


Figure 2: Resistive Switching Test Circuit & Waveforms

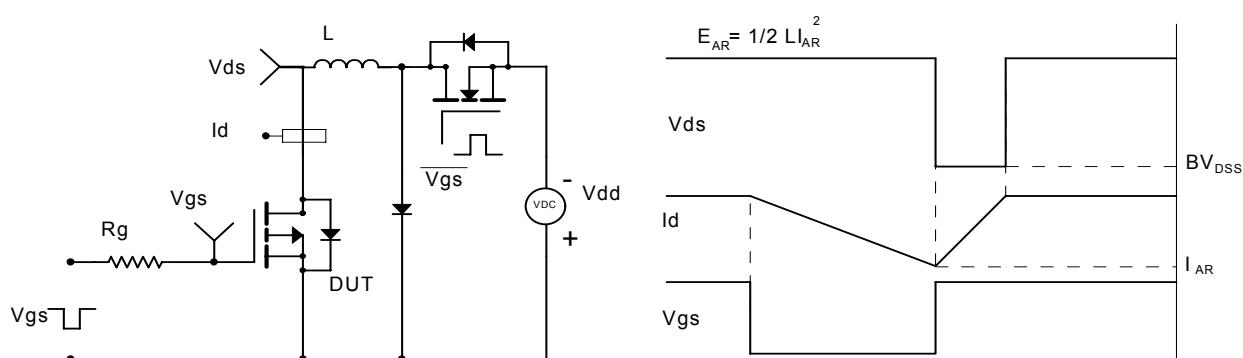
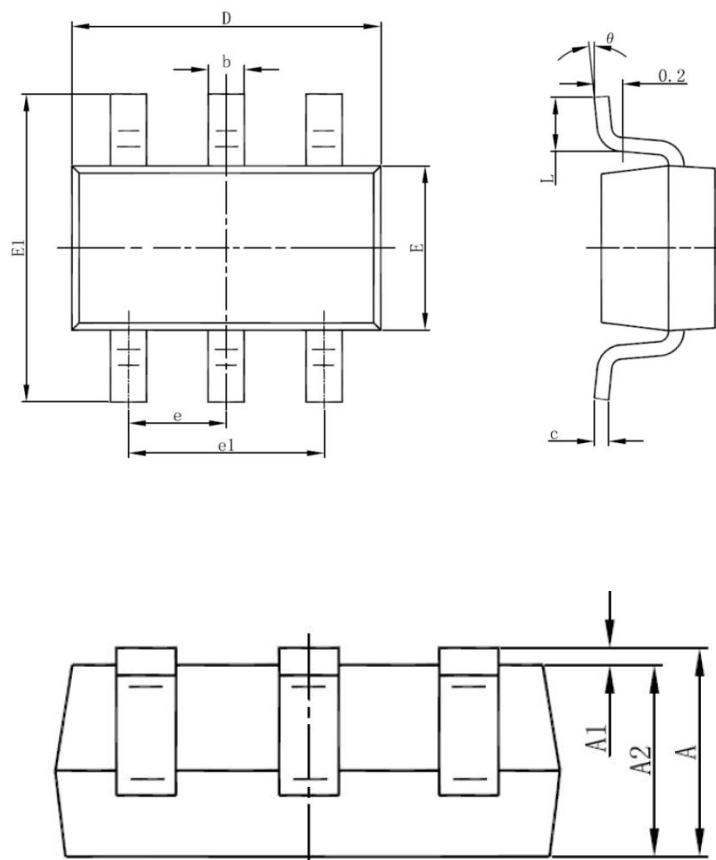


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

SOT-23-6L package



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°